

Meso-Machining

Manufacturing Technologies

Meso-machining technologies being developed at Sandia National Laboratories will help manufacturers improve a variety of production processes, tools, and components. Meso-machining will benefit the aerospace, automotive, biomedical, and defense industries by creating feature sizes from the 1 to 50 micron range.

Sandia's Manufacturing Science and Technology Center is developing the following meso-machining technologies:

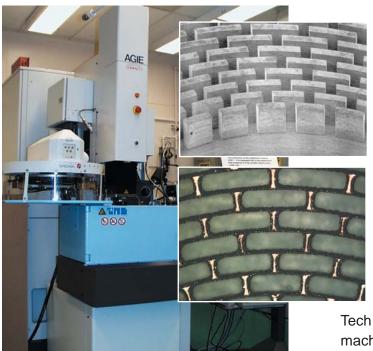
- Focused ion beam (FIB) machining,
- Micro-milling and -turning,
- Femto-second laser machining
- Micro-Electro Discharge Machining (Micro-EDM).

These technologies complement Sandia's existing micro-scale technologies such as silicon-based micro-machining and LIGA (electroforming). The various meso-scale processes have different material capabilities and machining performance specifications such as minimum feature size, feature tolerance, feature location accuracy, surface finish and material removal rate.

Sandia's Manufacturing Science and Technology Center is pursuing partnership projects with universities and industry to further develop meso-manufacturing technologies to help fulfill national security objectives. A partnership with Louisiana

Tech University worked on an FIB project to ion machine micro-end mills and micro-turning tools. The FIB is capable of machining nano-scale features in a variety of metals. Sandia is also partnering with Purdue University to research micro-EDM.

The Center is developing processes to manufacture parts in specialized materials that cannot be



Sandia's Micro-Electro Discharge Machine (Micro-EDM) (above). On the upper right inset is the Micro-EDM electrode in copper that was made with the LIGA (electroforming) process. On the lower right inset is a screen fabricated into .006 inch kovar sheet using the Micro-EDM electrode. The walls of the screen are .002 inch wide by .006 inch deep.



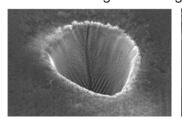


obtained either in commercial markets or through U.S. Department of Energy production facilities. For instance, work is being conducted to fabricate subminiature parts with nonplanar features from engineering materials such as steels, Kovar, plastics, ceramics and rare earth magnets.

Capabilities

Sandia can machine both 2-D and 3-D, micron-sized features in engineering materials such as ferrous metals and ceramics. Our advanced meso-machining processes also can complement micro-fabrication in such applications as:

- Fluidic circuits
- MEMs packaging
- Micro-valves
- Particle filters
- Subminiature actuators and motors
- Wafer slicing and dicing





In collaboration with Pulsed Power Sciences, the two left photos show how 20 micron wide micro holes drilled by a Ti sapphire system (120 Femtoseconds) in air (left) and in a vacuum (middle). These are compared with (right) a hole drilled by an Nd: YAG laser (λ = 1.06 μ m; pulse width = 100 nanoseconds, P = 50 mW, 2kHz). All images were taken from the entry side of the Kovar foil



ing. The end mill was used to make this 25-µm wide x

25-µm deep channel (above) in aluminum.

Sandia's Micro-sinker EDM is being used to extend the material base for LIGA. The LIGA process is used to fabricate subminiature, high-precision copper electrodes. The Micro-EDM uses these copper electrode tools to plunge into materials such as kovar or stainless steels. Our Microwire EDM is capable of machining with 25 micron

diameter wire and has positional accuracy of ± 1.5 microns.

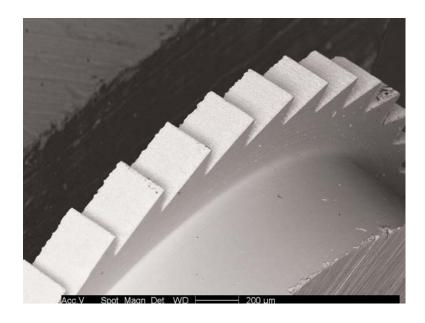
Resources

Sandia has developed a femto-second laser machining workstation. This technology is capable of machining deep

micron size holes in a variety of materials with practically no debris. Femto-second laser machining has an impressive material removal rate while avoiding thermal damage.



Meso-scale stepper motor machined by Micro-EDM process. Stepper motor size is 10 mm x 10 mm x 5 mm. The Micro-EDM enables high performance motors by machining difficult materials such as Neodymium iron boron and Hiperco ® alloy.



Accomplishments

- Blending silicon-based Micro Electro
 Mechanical Systems (MEMS) with meso machining technologies. Computer numerically
 controlled micromachines are multi-degree of
 freedom stages fabricated in polysilicon
 enabled by parallel kinematic mechanisms and
 driven by electrostatic linear stepper motors.
- Electromicrofluidic packaging is enabling a scale factor of approximately 1,000 that exists between small, standard fluidic connectors (microliters) and fluid channels on the silicon based electromicrofluidic IC (nanoliters).

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